(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
8 November 2001 (08.11.2001)

PCT

(10) International Publication Number
WO 01/84894 A1

(51) International Patent Classification[7]: H05K 1/02

(21) International Application Number: PCT/US01/40448

(22) International Filing Date: 3 April 2001 (03.04.2001)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
09/564,144 3 May 2000 (03.05.2000) US

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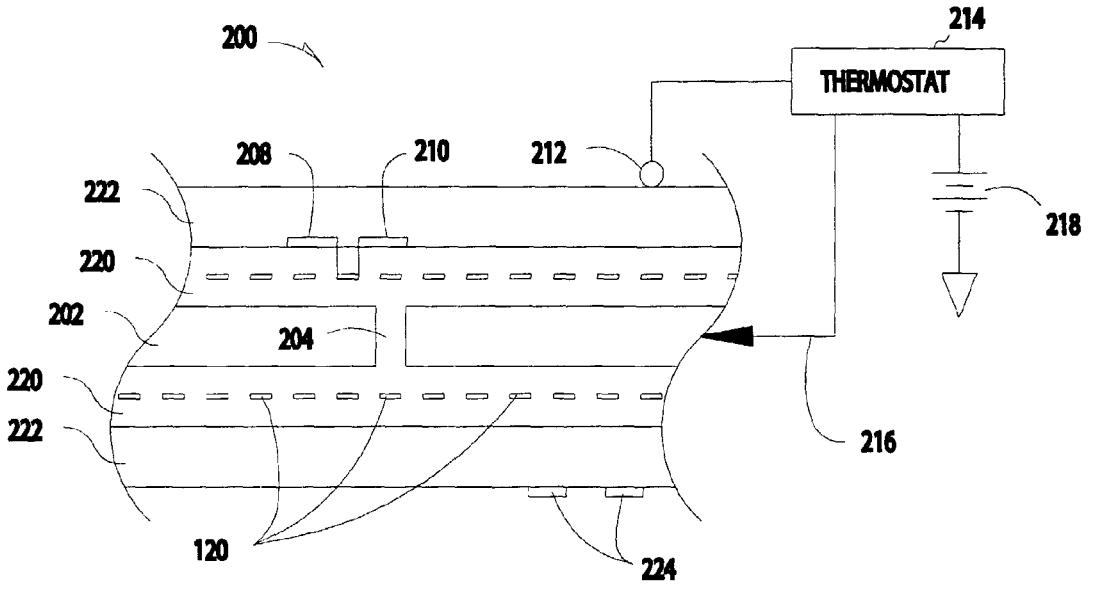
(81) Designated States *(national)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CR, CU, CZ, DE, DK, DM, DZ, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZW.

(84) Designated States *(regional)*: ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report*
— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

[Continued on next page]

(54) Title: CIRCUIT CARD ASSEMBLY HAVING CONTROLLED EXPANSION PROPERTIES



(57) Abstract: Piezoelectric material (120) is embedded in epoxy layers (220) of circuit cards (102) to control thermal expansion and contraction as a function of temperature changes. A temperature sensor (212) and thermostat (214) generates a controlled voltage as a function of temperature and applies the voltage to piezoelectric blocks (120) within the circuit card. Local areas of the circuit card can have different amounts of piezoelectric material (120) or different thermostats (214). Piezoelectric blocks (120) can be arranged in regular patterns or can be randomly or pseudorandomly placed.

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